Integrated AC LED Solution

Acrich2 - 8.7W

SMJE-XV08W1P3













## **Product Brief**

#### **Description**

- The Acrich2 series of products are designed to be driven directly off of AC line voltage, therefore they do not need the standard converter essential for conventional general lighting products.
- The converter or driver found in most general lighting products can limit the overall life of the product, but with the Acrich2 series of products the life of the product can more closely be estimated from the LED itself. This will also allow for a much smaller form factor from an overall fixture design allowing for higher creativity in the fixture.
- The modules have a high power factor which can contribute to a higher energy savings in the end application.

#### **Features and Benefits**

- Connects directly to AC line voltage
- High Power Efficiency & Factor
- Low THD
- Long Life Time
- Simple BOM
- Miniaturization
- Lead Free Product
- RoHS Compliant

#### **Key Applications**

- Bulb Llight
- Down Light
- Factory Ceiling Light
- Industrial Light

**Table 1. Product Selection (CCT)** 

Dowt No.	Vin [Van]	D IWI	Color	CCT IKI	CRI
Part No.	Vin [Vac]	P [W]	Color	CCT [K]	Min.
SMJE-2V08W1P3	120		Cool	4700 – 6000	
	-	8.7	Neutral	3700 – 4200	80
SMJE-3V08W1P3	220		Warm	2600 – 3200	

Table 2. Product Selection (Flux)

Part No.	Vin [Voc]	D [W]	Flux Bin	Flux [lm]		
rait No.	Vin [Vac]	P [W]	FIUX BIII	Min.	Тур.	
SMJE-2V08W1P3	120	0.7	8a	590	650	
SMJE-3V08W1P3	220	8.7	8b	740	800	



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Company Information

## **Performance Characteristics**

Table 3. Electro Optical Characteristics, T<sub>a</sub> = 25<sup>o</sup>C

Dawawatan	Completed		Value		Unit	Mark	
Parameter	Symbol	Min.	Тур.	Max.	Unit	Mark	
Luminous Flux	Φ <sub>V</sub> <sup>[2]</sup>	590	650	740	. Im	8a	
Luminous Flux	$\Phi_{V^{1-j}}$	740	800	870	· Im	8b	
		5300	5600	6000		В	
		4700	5000	5300	•	С	
Correlated Color Temperature [3]	CCT	3700	4000	4200	K	E	
,		2900	3000	3200	•	G	
		2600	2700	2900	•	Н	
CRI	Ra	80	-	-	-		
Laurent Malkania [4]			120		Mari	2V	
Input Voltage [4]	$V_{in}$		220		· Vac	3V	
Power Consumption	Р	8.2	8.7	9.1	W	08W	
Operating Frequency	f		50 / 60		Hz		
Power Factor	PF		Over 0.95		-		
Viewing Angle	2O <sub>1/2</sub>		120		deg.		

#### Notes:

- (1) At 120 Vac/220 Vac,  $T_a = 25^{\circ}\text{C}$
- (2)  $\Phi_V$  is the total luminous flux output measured with an integrated sphere.
- (3) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.
- (4) Operating Voltage doesn't indicate the maximum voltage which customers use but means tolerable voltage according to each country's voltage variation rate. It is recommended that the solder pad temperature should be below 70  $^{\circ}$ C.

# **Absolute Maximum Ratings**

Table 4. Absolute Maximum Ratings,  $T_a = 25$ °C

Parameter	Symbol	Unit	Value
Maximum Input Voltage @120Vac	V	\/	140
Maximum Input Voltage @220Vac	$V_{in}$	Vac	264
Power Consumption	Р	W	11.5
Operating Temperature	$T_{opr}$	ōС	-30 ~ 85
Storage Temperature	T <sub>stg</sub>	ōС	-40 ~ 100
ESD Sensitivity	-	-	±4,000V HBM

## **Thermal Resistance**

Part	Package Power Dissipation [W]	Maximum Junction Temperature [℃]	Rθ <sub>j-s</sub> [℃/W]
Acrich2 LED	SAW8KG0B Max 0.58	125	27

The Acrich2 LED has a thermal resistance of 27  $^{\circ}\text{C/W}$  from junction of the LED to the

LED lead.

The maximum junction temperature of the Acrich2 LED package is 125  $^{\circ}$ C, therefore the maximum lead temperature T<sub>s\_max</sub> is

$$T_{s_{max}} = T_{j_{max}} - (R\theta_{j_{r}s} * P_{d})$$
  
= 125°C - (27°C/W \* 0.58W) = 109.34°C

Although this is the maximum lead temperature, it is recommended to keep the lead temperature under 70  $^{\circ}$ C.



# **Relative Spectral Distribution**

Fig 1. Relative Spectral Distribution vs. Wavelength Characteristic - G, H

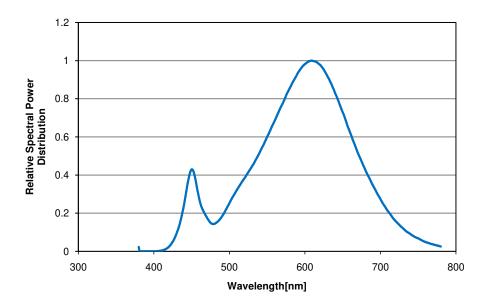
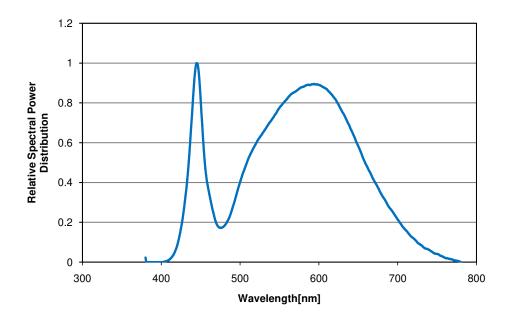
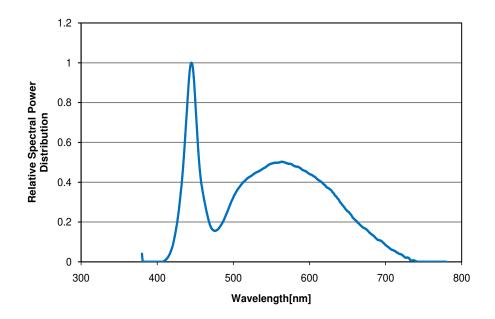


Fig 2. Relative Spectral Distribution vs. Wavelength Characteristic - E

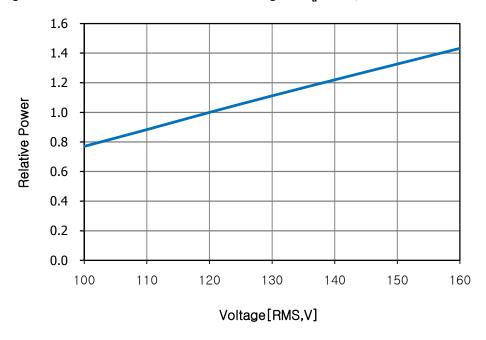


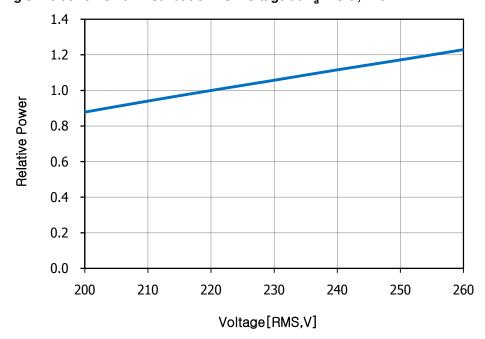
# **Relative Spectral Distribution**

Fig 3. Relative Spectral Distribution vs. Wavelength Characteristic - B, C



## **Relative Power Distribution**





## **Relative Luminous Distribution**

Fig 6. Relative Luminous Flux vs. Voltage at  $T_a$  =25  $^{\circ}$ C, 120V

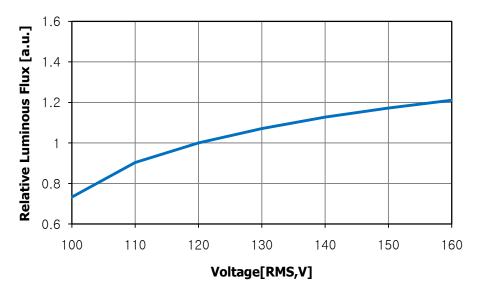
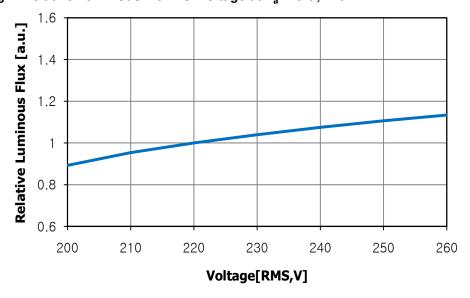
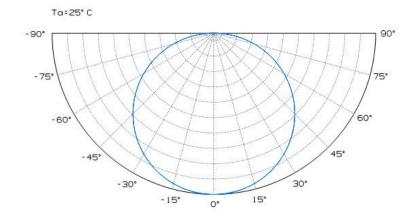


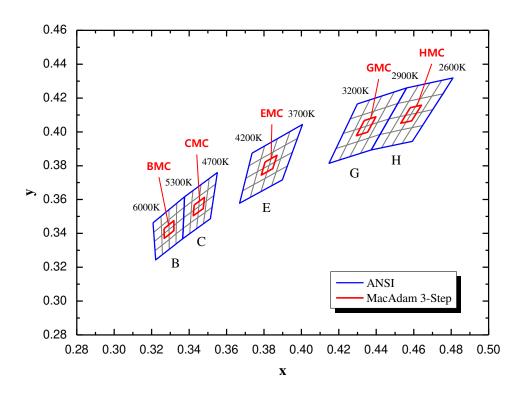
Fig 7. Relative Luminous Flux vs. Voltage at  $T_a$  =25  $^{\circ}$ C, 220V



# **Luminous Flux Characteristics**

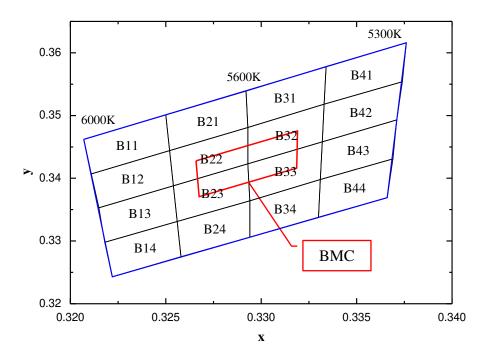


## **Color Bin Structure**



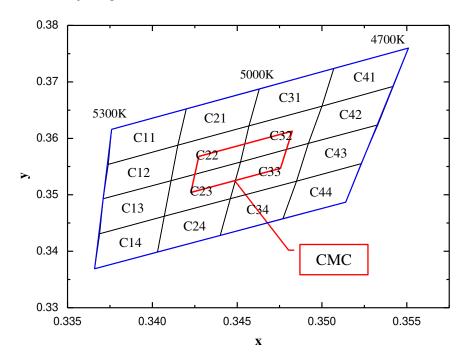
Bin	x	у	Bin	x	у	Bin	x	у
	0.3266	0.3428		0.3427	0.3568		0.3806	0.3822
ВМС	0.3268	0.3371	- CMC	0.3423	0.3504	EMC	0.3786	0.3745
BIVIC	0.3319	0.3416	CIVIC	0.3476	0.3547	EIVIC	0.3846	0.3782
	0.3319	0.3476		0.3482	0.3613		0.3870	0.3861
	0.4336	0.4067		0.4581	0.4143			
GMC	0.4294	0.3977	- HMC	0.4531	0.4051			
GIVIC	0.4354	0.3999	- HWC	0.4589	0.4065			
	0.4398	0.4089	_	0.4641	0.4157			





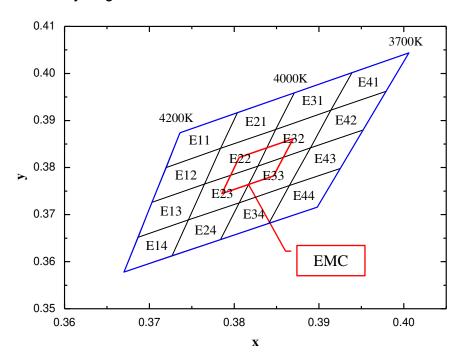
Bin	x	у	Bin	x	у	Bin	х	у	Bin	x	у
	0.3207	0.3462		0.3250	0.3501		0.3292	0.3539		0.3334	0.3578
B11	0.3211	0.3407	B21	0.3252	0.3444	B31	0.3293	0.3481	B41	0.3333	0.3518
611	0.3252	0.3444	D2 I	0.3293	0.3481	DSI	0.3333	0.3518	D4 I	0.3374	0.3554
	0.3250	0.3501		0.3292	0.3539		0.3334	0.3578		0.3376	0.3616
	0.3211	0.3407		0.3252	0.3444		0.3293	0.3481		0.3333	0.3518
B12	0.3215	0.3353	B22	0.3254	0.3388	B32	0.3293	0.3423	B42	0.3332	0.3458
B12	0.3254	0.3388	DZZ	0.3293	0.3423	<b>D</b> 32	0.3332	0.3458	D42	0.3371	0.3493
	0.3252	0.3444		0.3293	0.3481		0.3333	0.3518		0.3374	0.3554
	0.3215	0.3353		0.3254	0.3388		0.3293	0.3423		0.3332	0.3458
B13	0.3218	0.3298	B23	0.3256	0.3331	B33	0.3294	0.3364	B43	0.3331	0.3398
БІЗ	0.3256	0.3331	DZS	0.3294	0.3364	DSS	0.3331	0.3398	D43	0.3369	0.3431
	0.3254	0.3388		0.3293	0.3423		0.3332	0.3458		0.3371	0.3493
	0.3218	0.3298		0.3256	0.3331		0.3294	0.3364		0.3331	0.3398
B14	0.3222	0.3243	B24	0.3258	0.3275	B34	0.3294	0.3306	B44	0.3330	0.3338
514	0.3258	0.3275	D24	0.3294	0.3306	D34	0.3330	0.3338	D44	0.3366	0.3369
	0.3256	0.3331		0.3294	0.3364		0.3331	0.3398		0.3369	0.3431





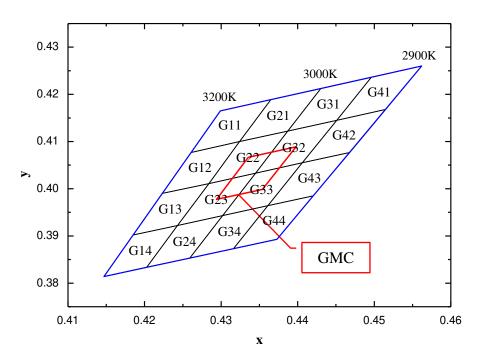
Bin	x	у	Bin	x	у	Bin	х	у	Bin	x	у
	0.3376	0.3616		0.3420	0.3652		0.3463	0.3687		0.3507	0.3724
C11	0.3374	0.3554	C21	0.3415	0.3588	C21	0.3457	0.3622	C41	0.3500	0.3657
	0.3415	0.3588	021	0.3457	0.3622	C31	0.3500	0.3657	U41	0.3542	0.3692
	0.3420	0.3652		0.3463	0.3687		0.3507	0.3724		0.3551	0.3760
	0.3374	0.3554		0.3415	0.3588		0.3457	0.3622		0.3500	0.3657
C12	0.3371	0.3493	C22	0.3411	0.3525	C32	0.3452	0.3558	C42	0.3492	0.3591
CIZ	0.3411	0.3525	<b>G22</b>	0.3452	0.3558	U32	0.3492	0.3591	C42	0.3533	0.3624
	0.3415	0.3588		0.3457	0.3622		0.3500	0.3657		0.3542	0.3692
	0.3371	0.3493		0.3411	0.3525		0.3452	0.3558		0.3492	0.3591
C13	0.3369	0.3431	C23	0.3407	0.3462	C33	0.3446	0.3493	C43	0.3485	0.3524
013	0.3407	0.3462	023	0.3446	0.3493	CSS	0.3485	0.3524	U43	0.3523	0.3555
	0.3411	0.3525		0.3452	0.3558		0.3492	0.3591		0.3533	0.3624
	0.3369	0.3431		0.3407	0.3462		0.3446	0.3493		0.3485	0.3524
C14	0.3366	0.3369	C24	0.3403	0.3399	C34	0.3440	0.3428	C44	0.3477	0.3458
	0.3403	0.3399	024	0.3440	0.3428	034	0.3477	0.3458	044	0.3514	0.3487
	0.3407	0.3462		0.3446	0.3493		0.3485	0.3524		0.3523	0.3555





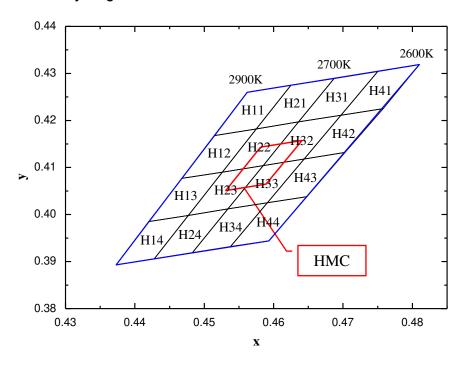
Bin	x	у	Bin	x	у	Bin	х	у	Bin	x	у
	0.3736	0.3874		0.3804	0.3917		0.3871	0.3959		0.3939	0.4002
E11	0.3720	0.3800	E21	0.3784	0.3841	E21	0.3849	0.3881	E41	0.3914	0.3922
= ''	0.3784	0.3841	EZI	0.3849	0.3881	E31	0.3914	0.3922	E41	0.3979	0.3962
	0.3804	0.3917		0.3871	0.3959		0.3939	0.4002		0.4006	0.4044
	0.3720	0.3800		0.3784	0.3841		0.3849	0.3881		0.3914	0.3922
E12	0.3703	0.3726	E22	0.3765	0.3765	E32	0.3828	0.3803	E42	0.3890	0.3842
E12	0.3765	0.3765	<b>E22</b>	0.3828	0.3803	E32	0.3890	0.3842	E42	0.3952	0.3880
	0.3784	0.3841		0.3849	0.3881		0.3914	0.3922		0.3979	0.3962
	0.3703	0.3726		0.3765	0.3765		0.3828	0.3803		0.3890	0.3842
E13	0.3687	0.3652	E23	0.3746	0.3689	E33	0.3806	0.3725	E43	0.3865	0.3762
EIS	0.3746	0.3689	E23	0.3806	0.3725	ESS	0.3865	0.3762	E43	0.3925	0.3798
	0.3765	0.3765		0.3828	0.3803		0.3890	0.3842		0.3952	0.3880
	0.3687	0.3652		0.3746	0.3689		0.3806	0.3725		0.3865	0.3762
E14	0.3670	0.3578	E24	0.3727	0.3613	E34	0.3784	0.3647	E44	0.3841	0.3682
E14	0.3727	0.3613	E24	0.3784	0.3647	E34	0.3841	0.3682	E44	0.3898	0.3716
	0.3746	0.3689		0.3806	0.3725		0.3865	0.3762		0.3925	0.3798





Bin	x	у	Bin	x	у	Bin	x	у	Bin	х	у
	0.4299	0.4165		0.4364	0.4188		0.4430	0.4212		0.4496	0.4236
G11	0.4261	0.4077	G21	0.4324	0.4099	G31	0.4387	0.4122	G41	0.4451	0.4145
GII	0.4324	0.4100	GZI	0.4387	0.4122	GSI	0.4451	0.4145	G41	0.4514	0.4168
	0.4365	0.4189		0.4430	0.4212		0.4496	0.4236		0.4562	0.4260
	0.4261	0.4077		0.4324	0.4100		0.4387	0.4122		0.4451	0.4145
G12	0.4223	0.3990	G22	0.4284	0.4011	G32	0.4345	0.4033	G42	0.4406	0.4055
GIZ	0.4284	0.4011	GZZ	0.4345	0.4033	G32	0.4406	0.4055	G42	0.4468	0.4077
	0.4324	0.4100		0.4387	0.4122		0.4451	0.4145		0.4515	0.4168
	0.4223	0.3990		0.4284	0.4011		0.4345	0.4033		0.4406	0.4055
G13	0.4185	0.3902	G23	0.4243	0.3922	G33	0.4302	0.3943	G43	0.4361	0.3964
d is	0.4243	0.3922	G23	0.4302	0.3943	GSS	0.4361	0.3964	G43	0.4420	0.3985
	0.4284	0.4011		0.4345	0.4033		0.4406	0.4055		0.4468	0.4077
	0.4243	0.3922		0.4302	0.3943		0.4302	0.3943		0.4361	0.3964
G14	0.4203	0.3834	G24	0.4259	0.3853	G34	0.4259	0.3853	G44	0.4316	0.3873
314	0.4147	0.3814	G24	0.4203	0.3834	G34	0.4316	0.3873	G44	0.4373	0.3893
	0.4185	0.3902		0.4243	0.3922		0.4361	0.3964		0.4420	0.3985





Bin	x	у	Bin	x	у	Bin	x	у	Bin	x	у
	0.4562	0.4260		0.4625	0.4275		0.4687	0.4289		0.4750	0.4304
H11	0.4515	0.4168	H21	0.4575	0.4182	H31	0.4636	0.4197	H41	0.4697	0.4211
"''	0.4575	0.4182	П21	0.4636	0.4197	пот	0.4697	0.4211	П41	0.4758	0.4225
	0.4625	0.4275		0.4687	0.4289		0.4750	0.4304		0.4810	0.4319
	0.4515	0.4168		0.4575	0.4182		0.4636	0.4197		0.4697	0.4211
H12	0.4468	0.4077	H22	0.4526	0.4090	H32	0.4585	0.4104	H42	0.4644	0.4118
піг	0.4526	0.4090	П22	0.4585	0.4104	ПЗ2	0.4644	0.4118	П42	0.4703	0.4132
	0.4575	0.4182		0.4636	0.4197		0.4697	0.4211		0.4758	0.4225
	0.4468	0.4077		0.4526	0.4090		0.4585	0.4104		0.4644	0.4118
ш	0.4420	0.3985	шоо	0.4477	0.3998	шаа	0.4534	0.4012	H43	0.4591	0.4025
H13	0.4477	0.3998	H23	0.4534	0.4012	H33	0.4591	0.4025	п43	0.4648	0.4038
	0.4526	0.4090		0.4585	0.4104		0.4644	0.4118		0.4703	0.4132
	0.4420	0.3985		0.4477	0.3998		0.4534	0.4012		0.4591	0.4025
H14	0.4373	0.3893	<b>⊔</b> 24	0.4428	0.3906	<b>⊔</b> 24	0.4483	0.3919	шии	0.4538	0.3932
114	0.4428	0.3906	H24	0.4483	0.3919	H34	0.4538	0.3932	H44	0.4593	0.3944
	0.4477	0.3998		0.4534	0.4012		0.4591	0.4025		0.4648	0.4038

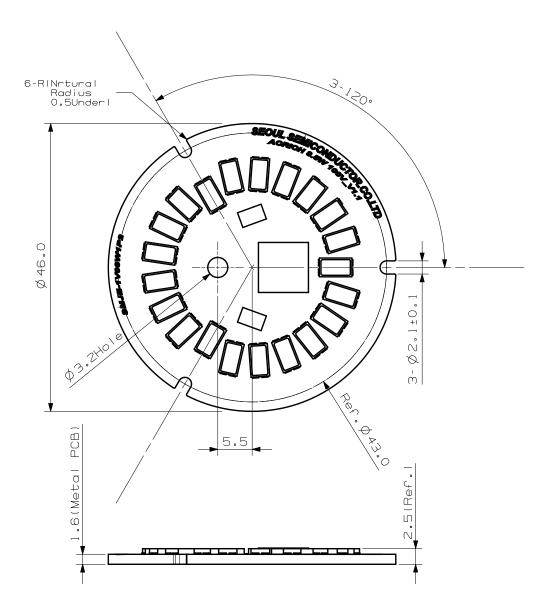
## **Part List**

#### **Table 5. Part List**

No	Part	Reference	Specification	Quantity
1	PCB	-	Al, ø46, T=1.6, 1 layer / Cu 1oz / White PSR	1
2	LED	-	SAW8KG0B	21
	10	114	MAH3082 @120Vac	1
3	IC	U1	MAH3080 @220Vac	1



## **Mechanical Dimensions**

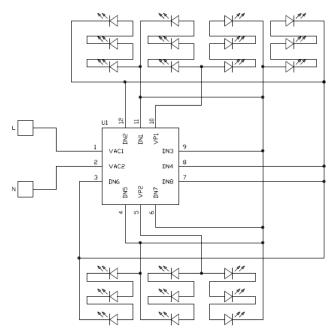


#### Notes

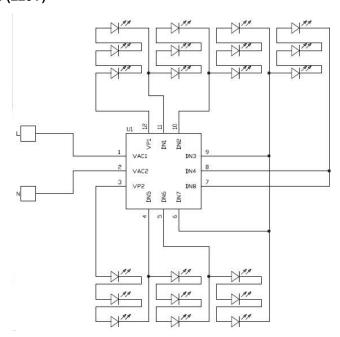
- (1) All dimensions are in millimeters. (Tolerance :  $\pm 0.2$ )
- (2) Scale: None

# **Circuit Drawing**

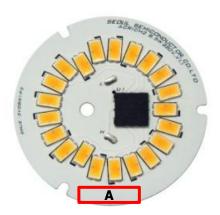
#### SMJE-2V08W1P3 (120V)



#### SMJE-3V08W1P3 (220V)



# **Marking Information**



### A: Marking

#### (1) Single Bin

A: ex) 140101 Z4G32

- Description

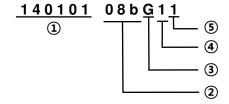
$$\frac{140101}{1} \quad \frac{Z4G32}{2}$$

- ① SMT Date (YYMMDD, 6 Digits)
- 2 LED PKG. Luminous Intensity Bin (2 Digits)
- 3 LED PKG. Color Bin (3 Digits)

#### (2) Combination Bin

**A:** ex) 140101 08bG11

- Description



- ① SMT Date (YYMMDD, 6 Digits)
- 2 Module Flux Bin (3 Digits)
- 3 CCT (1 Digit)
- 4 CCT Combination NO. (1 Digit)
- 5 VF Combination NO. (1 Digit)

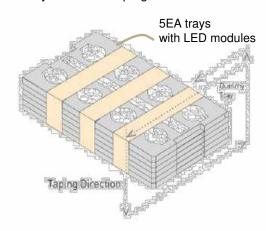
② Module Flux Bin				<u>3</u> ССТ				④ CCT Combination			⑤ VF Combination		
Mark	Min.	Тур.	Max.	Mark	Min.	Тур.	Max.	Mark	Bin1	Bin2	Mark	Bin1	Bin2
08a	590	650	740	В	5300	5600	6000	0	22	33	1	Α	Α
08b	740	800	870	С	4700	5000	5300	1	23	32	2	Α	В
				E	3700	4000	4200	2	33	22	3	В	Α
				G	2900	3000	3200	3	32	23	4	Α	С
				Н	2600	2700	2900	4	МС	MC	5	С	Α
											6	В	В
											7	В	С
											8	С	В
											9	С	С

# **Packing**

#### 1. Tray information

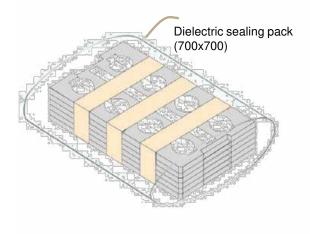


- 50 PCS LED modules packed per tray
- 2. Tray stack and taping

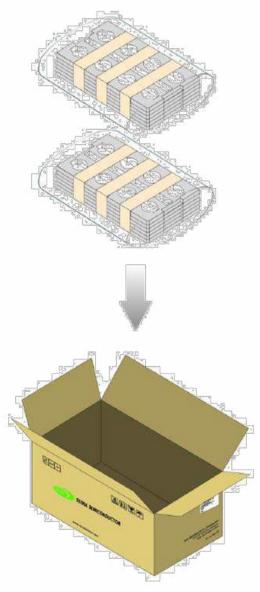


- 5 LED module trays and additional 2 dummy trays each up and down of box
- Add silica gel (1EA) on top of the tray

#### 3. Sealing packing



#### 4. Box information & packing



- 500 PCS modules per BOX 1EA
- \*\* 1 Box : 50 PCS per tray x 10 trays = 500 PCS

## **Label Information**

Model No.	SMJE-XV08W1P3 (1)					
Rank	XXXXXXX (2)					
Туре	STD / 3-Step (3)					
Quantity	XX					
Lot No.	YYMDDXXXXX-XXXXXXX					
SEOUL	SEOUL SEMICONDUCTOR CO.,LTD.					

#### **Notes**

(1) The model number designation is explained as follow

SMJE : Seoul Semiconductor internal code XV : Input Voltage (2V = 120V, 3V = 220V)

08W : About Power Consumption

1 : Acrich IC Version

P3: MJT PKG (SAW8KG0B)

(2) It represents the LED module rank.

ALL: Single Bin, 08a/08b: Combination Bin X06/X16: Each Sub-Bin NO. (X = CCT) A: Single Bin, M: Combination Bin(3-Step)

- (3) It represents single bin(STD) or MacAdam 3-Step(3-Step).
- (4) It is attached to the top of a sealing pack & the bottom right corner of the box.

# TOTAL Quantity III III III III XX



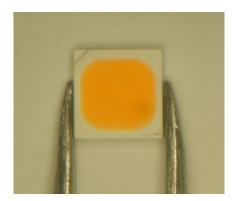
SEOUL SEMICONDUCTOR CO.,LTD.

#### **Notes**

(1) It is attached to the bottom right corner of the box.

## **Handling of Silicone Resin for LEDs**





- (1) Acrich2 series is encapsulated with silicone resin for high optical efficiency.
- (2) Please do not touch the silicone resin area with sharp objects such as pincette(tweezers).
- (3) Finger prints on silicone resin area may affect the performance.
- (4) Please store LEDs in covered containers to prevent dust accumulation as this may affect performance.
- (5) Excessive force more than 3000gf to the silicone lens can result in fatal or permanent damage with LEDs.
- (6) Please do not cover the silicone resin area with any other resins such as epoxy, urethane, etc.

## **Precaution for Use**

- (1) Please review the Acrich2 Application Note for proper protective circuitry usage.
- (2) Please note, Acrich2 products run off of high voltage, therefore caution should be taken when working near Acrich2 products.
- (3) Make sure proper discharge prior to starting work.
- (4) DO NOT touch any of the circuit board, components or terminals with body or metal while circuit is active.
- (5) Please do not add or change wires while Acrich2 circuit is active.
- (6) Long time exposure to sunlight or UV can cause the lens to discolor.
- (7) Please do not use adhesives to attach the LED that outgas organic vapor.
- (8) Please do not use together with the materials containing Sulfur.
- (9) Please do not assemble in conditions of high moisture and/or oxidizing gas such as Cl, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, NO<sub>x</sub>, etc.
- (10) Please do not make any modification on module.
- (11) Please be cautious when soldering to board so as not to create a short between different trace patterns.
- (12) Do not impact or place pressure on this product because even a small amount of pressure can damage the product. The product should also not be placed in high temperatures, high humidity or direct sunlight since the device is sensitive to these conditions.
- (13) When storing devices for a long period of time before usage, please following these guidelines:
  - \* The devices should be stored in the anti-static bag that it was shipped in from Seoul-Semiconductor with opening.
  - \* If the anti-static bag has been opened, re-seal preventing air and moisture from being present in the bag.
- (14) LEDs and IC are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). The Acrich2 product should also not be installed in end equipment without ESD protection. Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.
- a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is the defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to an LEDs may cause the product to demonstrate unusual characteristics such as:

## **Precaution for Use**

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event. One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:

- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

#### Environmental controls:

- Humidity control (ESD gets worse in a dry environment)

#### b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is subjected to a current or voltage that is beyond the maximum specification limits of the device. The effects from an EOS event can be noticed through product performance like:

- Changes to the performance of the LED package (If the damage is around the bond pad area and since the package is completely encapsulated the package may turn on but flicker show severe performance degradation.)
- Changes to the light output of the luminaire from component failure
- Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total circuit causing trickle down failures. It is impossible to predict the failure mode of every LED exposed to electrical overstress as the failure modes have been investigated to vary, but there are some common signs that will indicate an EOS event has occurred:

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse)
- Damage to the bond pads located on the emission surface of the LED package (shadowing can be noticed around the bond pads while viewing through a microscope)
- Anomalies noticed in the encapsulation and phosphor around the bond wires
- This damage usually appears due to the thermal stress produced during the EOS event
- c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing:
  - A surge protection circuit
  - An appropriately rated over voltage protection device
  - A current limiting device

## **Company Information**

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#### **Company Information**

Seoul Semiconductor (www.SeoulSemicon.com) manufacturers and packages a wide selection of light emitting diodes (LEDs) for the automotive, general illumination/lighting, Home appliance, signage and back lighting markets. The company is the world's fifth largest LED supplier, holding more than 10,000 patents globally, while offering a wide range of LED technology and production capacity in areas such as "nPola", "Acrich", the world's first commercially produced AC LED, and "Acrich MJT - Multi-Junction Technology" a proprietary family of high-voltage LEDs.

The company's broad product portfolio includes a wide array of package and device choices such as Acrich and Acirch2, high-brightness LEDs, mid-power LEDs, side-view LEDs, and through-hole type LEDs as well as custom modules, displays, and sensors.

#### **Legal Disclaimer**

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